

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- Higher operating power due to low thermal resistance
- Low conduction losses due to low on-state resistance
- Simple gate drive required due to low gate charge

1.3 Applications

- DC-to-DC convertors
- Notebook computers
- Portable equipment
- Switched-mode power supplies

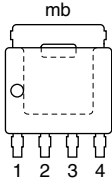
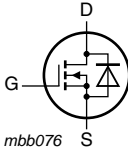
1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}; T_j \leq 150\text{ °C}$	-	-	30	V
I_D	drain current	$T_{mb} = 25\text{ °C}; V_{GS} = 10\text{ V};$ see Figure 1 and 3	-	-	67	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C};$ see Figure 2	-	-	62.5	W
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 5\text{ V}; I_D = 20\text{ A}; V_{DS} 10\text{ V};$ $T_j = 25\text{ °C};$ see Figure 11	-	5	-	nC
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 10\text{ A};$ $T_j = 25\text{ °C};$ see Figure 9 and 10	-	7.6	8.2	m Ω

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

SOT669 (LFPACK)

3. Ordering information

Table 3. Ordering information

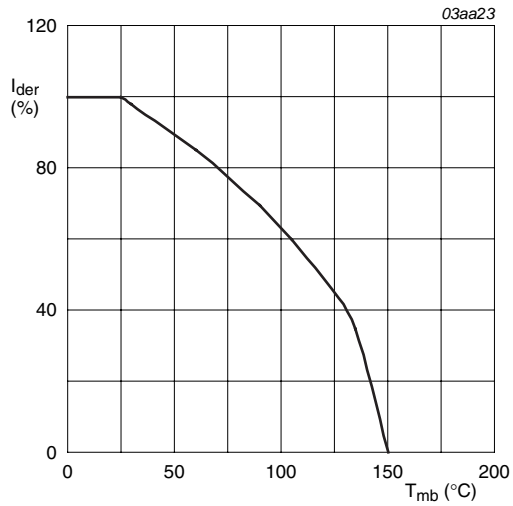
Type number	Package		Version
	Name	Description	
PH8230E	LFPACK	plastic single-ended surface-mounted package (LFPACK); 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

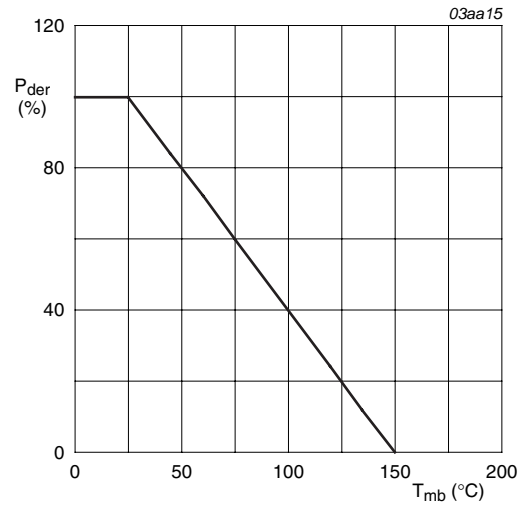
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 150\text{ °C}$	-	30	V
V_{GS}	gate-source voltage		-20	20	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 100\text{ °C}$; see Figure 1	-	42	A
		$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; see Figure 1 and 3	-	67	A
I_{DM}	peak drain current	$t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ °C}$; see Figure 3	-	268	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 2	-	62.5	W
T_{stg}	storage temperature		-55	150	°C
T_j	junction temperature		-55	150	°C
Source-drain diode					
I_S	source current	$T_{mb} = 25\text{ °C}$	-	52	A
I_{SM}	peak source current	$t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ °C}$	-	150	A
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ °C}$; $I_D = 33.9\text{ A}$; $V_{sup} = 30\text{ V}$; $t_p = 0.15\text{ ms}$; unclamped	-	115	mJ



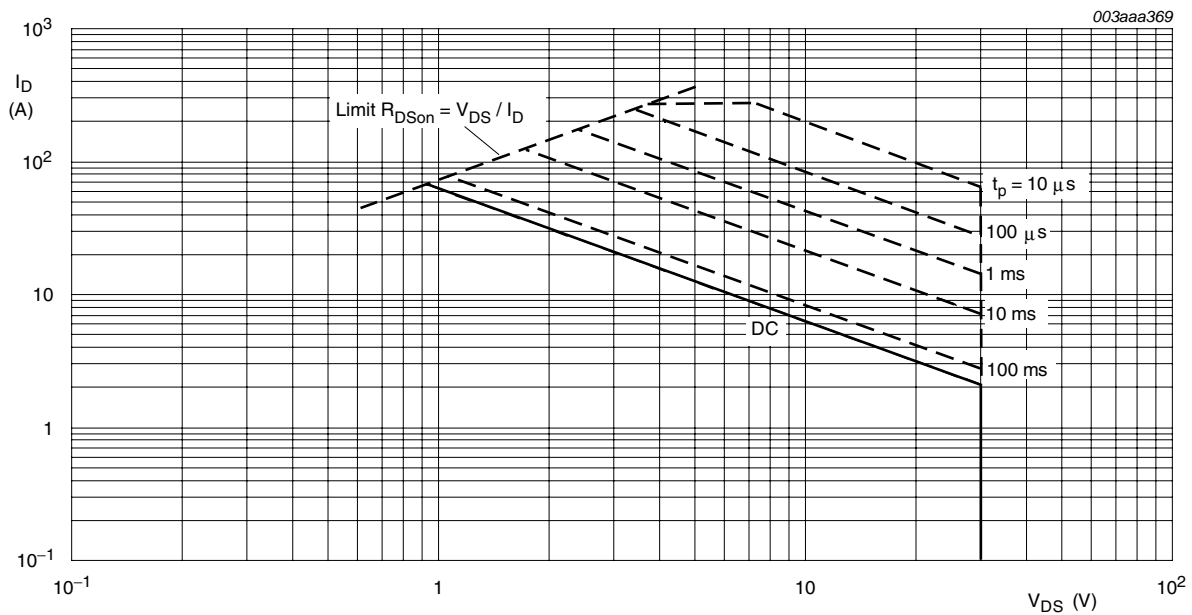
$$I_{der} = \frac{I_D}{I_{D(25^\circ\text{C})}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{mb} = 25^\circ\text{C}; I_{DM}$ is single pulse; $V_{GS} = 10\text{V}$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	2	K/W

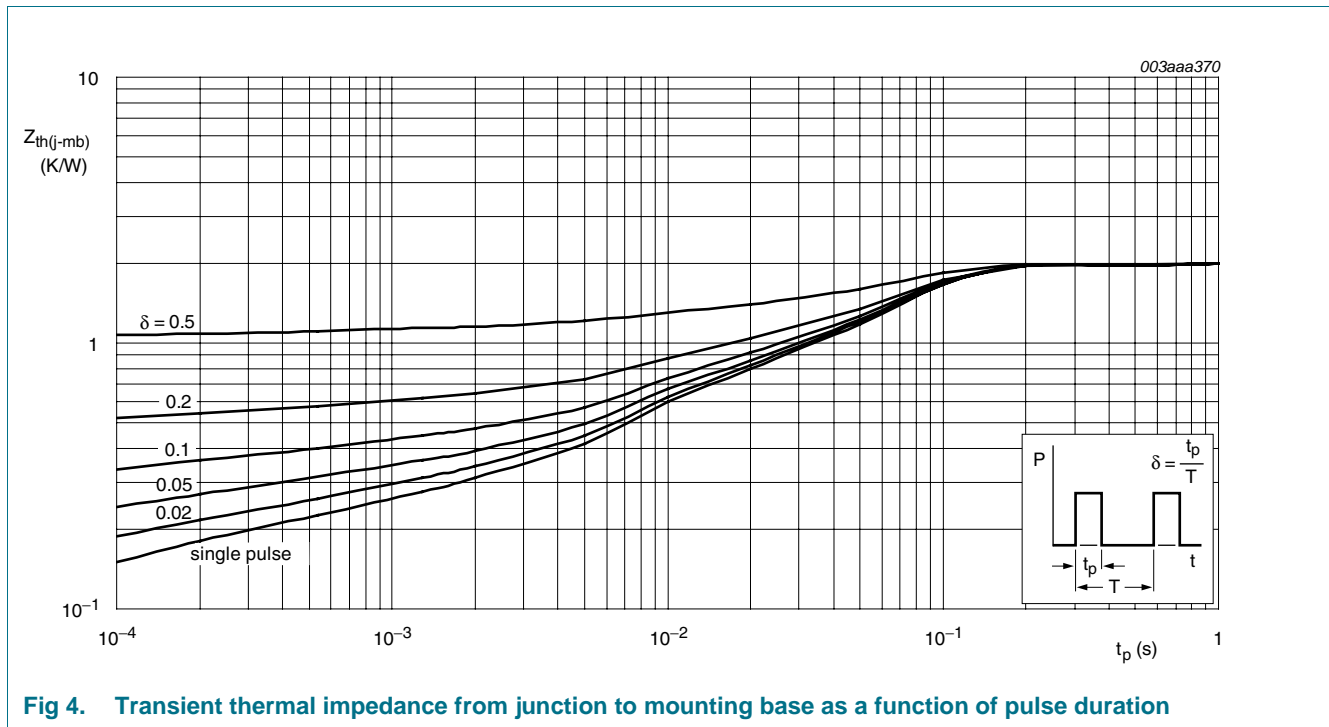


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	30	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 150 \text{ }^\circ C$; see Figure 8	0.5	-	-	V
		$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ C$; see Figure 8	1	1.7	2.5	V
I_{DSS}	drain leakage current	$V_{DS} = 30 V$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	0.06	1	μA
		$V_{DS} = 30 V$; $V_{GS} = 0 V$; $T_j = 150 \text{ }^\circ C$	-	-	500	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 V$; $V_{DS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	20	100	nA
		$V_{GS} = -20 V$; $V_{DS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	20	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 V$; $I_D = 10 A$; $T_j = 25 \text{ }^\circ C$; see Figure 9 and 10	-	7.6	8.2	m Ω
		$V_{GS} = 10 V$; $I_D = 10 A$; $T_j = 150 \text{ }^\circ C$; see Figure 9 and 10	-	13	14	m Ω
		$V_{GS} = 4.5 V$; $I_D = 10 A$; $T_j = 25 \text{ }^\circ C$; see Figure 10	-	11	13.2	m Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 20 A$; $V_{DS} = 10 V$; $V_{GS} = 5 V$; $T_j = 25 \text{ }^\circ C$; see Figure 11	-	14	-	nC
Q_{GS}	gate-source charge	$T_j = 25 \text{ }^\circ C$; see Figure 11	-	5.7	-	nC
Q_{GD}	gate-drain charge	$I_D = 20 A$; $V_{DS} = 10 V$; $V_{GS} = 5 V$; $T_j = 25 \text{ }^\circ C$; see Figure 11	-	5	-	nC
C_{iss}	input capacitance	$V_{DS} = 10 V$; $V_{GS} = 0 V$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ C$; see Figure 12	-	1400	-	pF
C_{oss}	output capacitance	$T_j = 25 \text{ }^\circ C$; see Figure 12	-	527	-	pF
C_{rss}	reverse transfer capacitance		-	235	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 10 V$; $R_L = 1.0 \Omega$; $V_{GS} = 4.5 V$; $R_{G(ext)} = 4.7 \Omega$; $T_j = 25 \text{ }^\circ C$; $I_D = 10 A$	-	28	-	ns
t_r	rise time		-	44	-	ns
$t_{d(off)}$	turn-off delay time		-	33	-	ns
t_f	fall time		-	21	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 10 A$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$; see Figure 13	-	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 20 A$; $di_S/dt = -100 A/\mu s$; $V_{GS} = 0 V$; $V_{DS} = 20 V$; $T_j = 25 \text{ }^\circ C$	-	38	-	ns

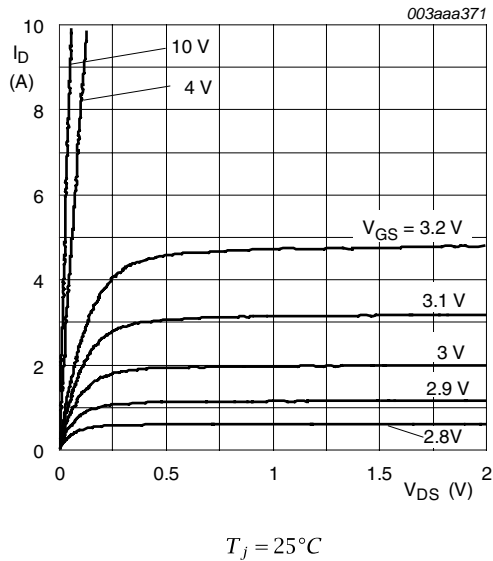


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

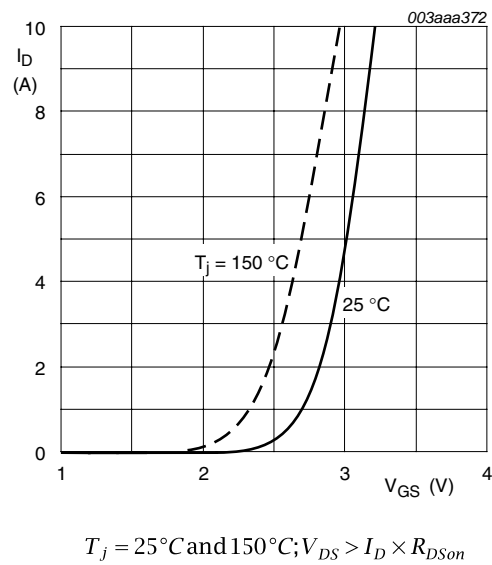


Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values

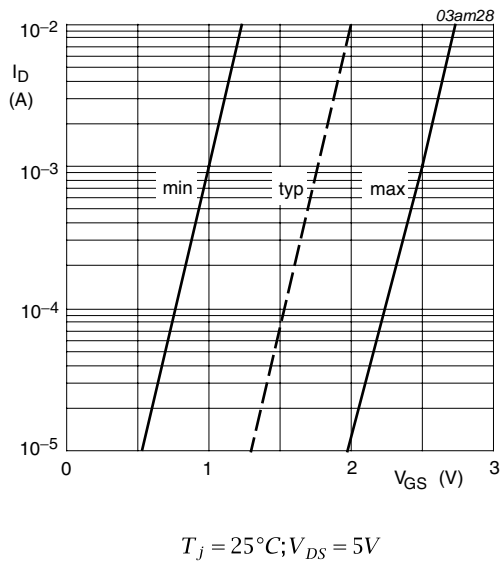


Fig 7. Sub-threshold drain current as a function of gate-source voltage

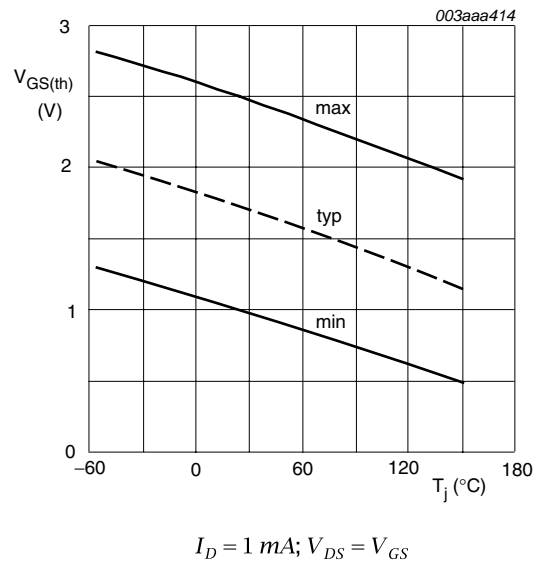
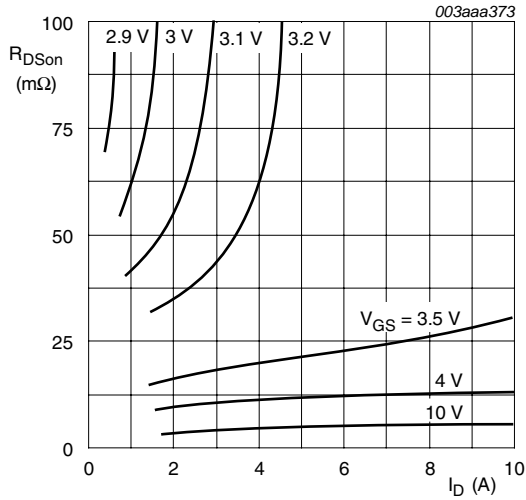
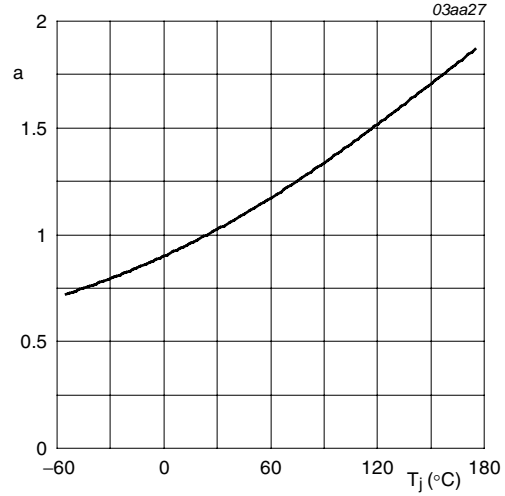


Fig 8. Gate-source threshold voltage as a function of junction temperature



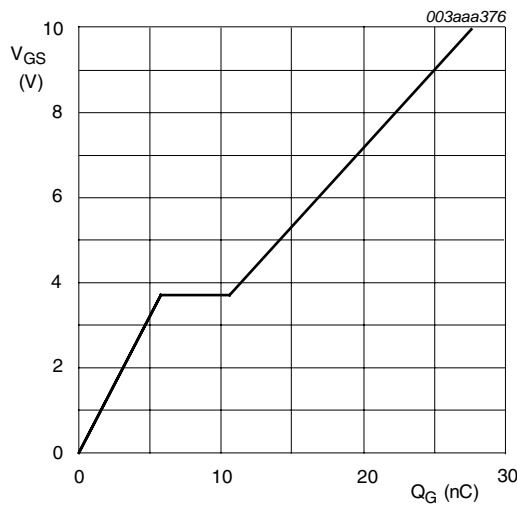
$T_j = 25^\circ C$

Fig 9. Drain-source on-state resistance as a function of drain current; typical values



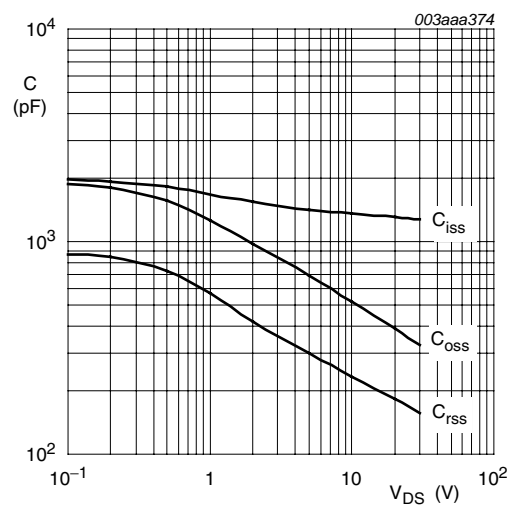
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ C)}}$$

Fig 10. Normalized drain-source on-state resistance factor as a function of junction temperature



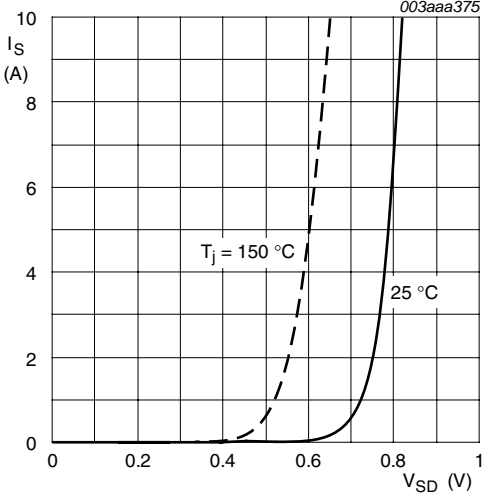
$I_D = 20A; V_{DS} = 10V$

Fig 11. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0V; f = 1MHz$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}$ and $150^\circ\text{C}; V_{GS} = 0\text{V}$

Fig 13. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (LFPAK); 4 leads

SOT669

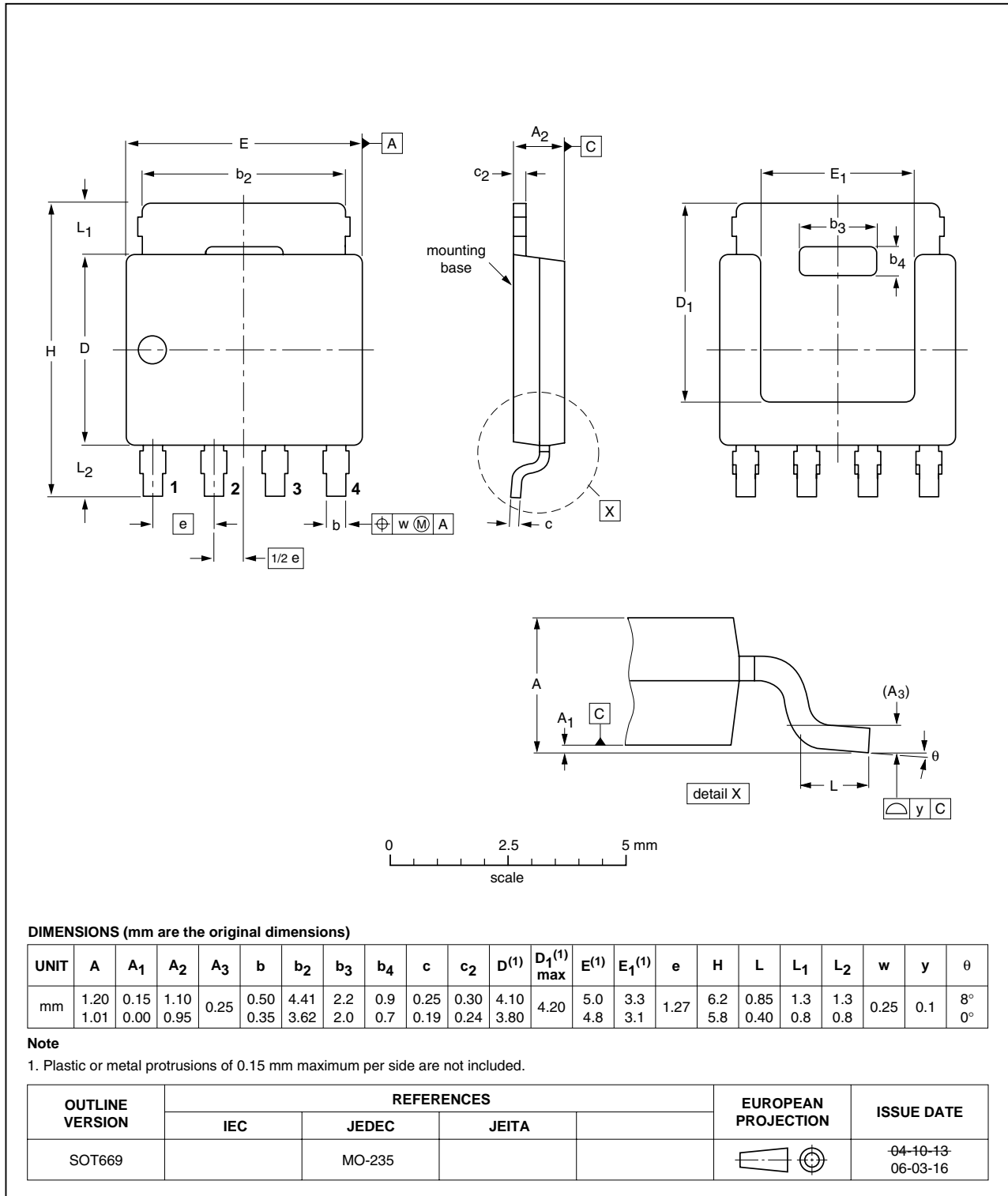


Fig 14. Package outline SOT669 (LFPAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PH8230E_4	20091117	Product data sheet	-	PH8230E-03
Modifications:		<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.		
PH8230E-03	20040302	Product data	-	PH8230E-02
PH8230E-02	20030429	Product data	-	PH8230E-01
PH8230E-01	20030304	Preliminary data	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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